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Connecting the Dots in Circular Lifecycle Management: *Industrial Data Sharing for Cognitive Analytics & Manufacturing*

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ZDM

IoT

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ICT for Sustainable Manufacturing Group

In ICT4SM Group we focus our research vision on ICT for Sustainable Manufacturing. The overall goal of sustainable manufacturing is to obtain a holistic view of product cycles in the manufacturing industry and optimise the life-cycle of manufacturing systems, products and services.

EPFL The current context: Linear Economy



- → Degradation of natural resources
- → Accumulation of waste
 - Increase in the world population
 - Increase in the consumption of goods

Unsustainable economy in the long term for humans and the environment

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EPFL The new context: Circular Economy



The problem: Degradation and Failure EPFL

- Resistance to Failure : An indicator of performance or condition
- **Potential Failure** : the starting point to observe the potential state or condition of not meeting a desirable or intended objective, and may be viewed as the opposite of success.
- Functional Failure : the starting point of the state or condition of not meeting a desirable or intended objective, and may be viewed as the opposite of SUCCESS.
- Premature failure
 - Premature P: Earlier Potential Failure than intended
 - **Premature F:** Earlier Functional Failure than intended
- Degradation Phases
 - Pre-P Period(<P)
 - P-F Interval(P-F)
 - Post-F Period(>F)







Defects are occurring and can be avoided at the **Shop-floor** level

Better and more efficient production management and operations, by better resource allocation, based on product & process quality measurements





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EPFL Understanding degradation: Model Based Systems Engineering



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EPFL Measuring degradation: with elements of intelligence/cognition of products

- Sensors (sensing)
- Memory chips (memory)

- Micro-processors + Software (logic)
- Barcodes, RFID, ... (identity)
- Bluetooth, WiFi, IoT, ... (communication)









EPFL Four Levels of Intelligence

- Intelligence Level 1: physical products without any embedded system (device or software). They do not interact with their environment.
- Intelligence Level 2: physical products with embedded simple sensors. Their embedded sensors allow them to interact with their environment.
- Intelligence Level 3: physical products with embedded sensors, memory and data processing capabilities. Such system of embedded devices and software (data processing) allows a product to adapt quickly to sophisticated changing environments.
- Intelligence Level 4: physical products with Product Embedded Information Devices (PEID). Examples of PEIDs are ID devices such as RFID tags, sensors or sensor networks, on board computers etc.



EPFL Intelligent Autonomous Products

- Intelligent Products may develop advanced intelligence capabilities and become Autonomous, since they have:
 - i. identity and, in addition to that, with their
 - ii. sensing & computing & communication capabilities, they may
 - iii. develop **reasoning** (at various levels of decision making, from local to distributed) and
 - iv. keep track of their history.

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 These elements are similar to the elements which allow us, humans, to develop our own "<u>intelligence</u>", "<u>cognition</u>" and "<u>autonomy</u>".





EPFL Systems of Systems: *Closed Loop Lifecycle Management*



https://publications.opengroup.org/c14b

https://publications.opengroup.org/c14a

- Lifecycle view: IoT is about managing all information about any Product/Thing
- Information is **Distributed OVER Systems** (devices, servers, applications, ...)
- Information is Distributed OVEr
 Organizations (companies, individuals, authorities, ...)
- Product (and its parts) are unique instances
- How to manage identities, access rights, ...?
- IoT should provide necessary capabilities for Closed Loop Lifecycle Management



Taking the LEAP: The Methods and Tools of the Linked Engineering and Manufacturing Platform (LEAP)

Industry 4.0 - RAMI 4.0 as enabler of Closed Loop Lifecycle Management EPFL



RAMI 4.0



EPFL It is all about Big Life Cycle Data Transformations

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EPFL Data Sharing for Manufacturing



White Papers

Published: 13 January 2020

Share to Gain: Unlocking Data Value in Manufacturing

White Papers

Emerging technologies such as advanced analytics and artificial intelligence (AI) are transforming the world of production. Although manufacturers are making strides in applying data-driven technologies, most focus on applications within their companies and have difficulty maximizing their return on investment. By sharing data across companies, manufacturers can unlock additional value and accelerate innovation. The potential value of data sharing simply by focusing on manufacturing process optimization has been estimated at over \$100 billion, based on best practices.

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EPFL The Meaning of Data



Ontologies allow the interpretation of the right meaning of data Reasoning Domain disambiguation Data Silos

EPFL The Meaning of Data is captured in *Ontologies*



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EPFL Ontologies & Big Data

Scattered data in several sources, systems and services

Different actors with multidisciplinary skills

Semantic modelling

Ontology design

(USM)

Ontology rules (inference)

module

Data

Domain knowledge



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EPFL Industrial Ontologies Foundry (IOF)

IOF as a source of principles and guidelines for Ontology **Design**, **Development** and **Use**

https://www.industrialontologies.org/



EPFL Sketch of a Product Life Cycle Ontology Framework

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EPFL Predictive Manufacturing Framework



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EPFL Cognitive Twins – vs - Digital Twins



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Thank you for your attention!



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